#### **INTEGRATED CIRCUITS**

## DATA SHEET

# **74F1604** Latch

Product specification

1990 Oct 04

IC15 Data Handbook





Latch 74F1604

#### **FEATURES**

- High impedance NPN base inputs for reduced loading (20μA in high and low state)
- Stores 16-bit wide data inputs, multiplexed 8-bit outputs
- Propagation delay 7.0ns typical
- Power supply current 70mA typical

#### **DESCRIPTION**

The 74F1604 is a dual octal transparent latch. Organized as 8–bit A and B latches, the latch outputs are connected by pairs to eight 2–input multiplexers. A select (SELECT A/B) input determines whether the A or B latch contents are multiplexed to the eight outputs. Data from the B inputs are selected when SELECT A/B is low; data from the A inputs are selected when SELECT A/B is high. Data enters the latch on the falling edge of the latch enable (LE) input. The latch remains transparent to the data inputs while LE is low, and stores the data that is present one setup time before the low–to–high latch enable transition.

TYPE	TYPICAL PROPAGATION DELAY	TYPICAL SUPPLY CURRENT (TOTAL)
74F1604	7.0ns	70mA

#### ORDERING INFORMATION

	ORDER CODE	
DESCRIPTION	COMMERCIAL RANGE	PKG DWG #
	$V_{CC} = 5V \pm 10\%,$ $T_{amb} = 0^{\circ}C \text{ to } +70^{\circ}C$	
28-pin plastic DIP	N74F1604N	SOT117-2
28-pin plastic SOL	N74F1604D	SOT136-1

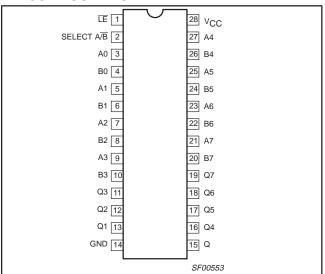
## INPUT AND OUTPUT LOADING AND FAN OUT TABLE

PINS	DESCRIPTION	74F (U.L.) HIGH/LOW	LOAD VALUE HIGH/LOW
A0 – A7	Data inputs	1.0/0.033	20μΑ/20μΑ
B0 – B7	Data inputs	1.0/0.033	20μΑ/20μΑ
SELECT A/B	Select input	1.0/0.033	20μΑ/20μΑ
ĪĒ	Latch enable input (active low)	1.0/0.033	20μΑ/20μΑ
Q0 – Q7	Data outputs	50/33	1.0mA/20mA

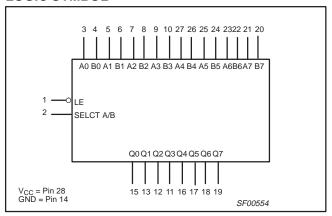
Note to input and output loading and fan out table

One (1.0) FAST unit load is defined as:  $20\mu\text{A}$  in the high state and 0.6mA in the low state.

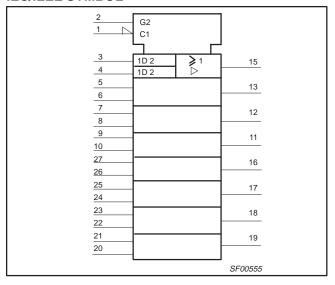
#### **PIN CONFIGURATION**



#### **LOGIC SYMBOL**

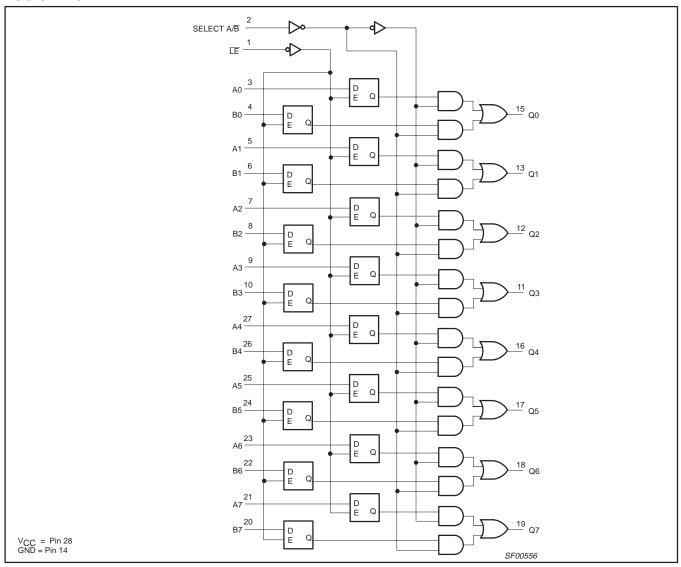


#### **IEC/IEEE SYMBOL**



74F1604 Latch

#### **LOGIC DIAGRAM**



#### **FUNCTION TABLE**

	INPUTS		OUTPUTS	OUTPUTS	
OPERATING MODE					
A0 – A7	B0 –B7	SELECT A/B	LE	Q0 – Q7	
A data	B data	L	L	B data	Enable and read register
A data	B data	Н	L	A data	Enable and read register
Х	Х	Х	Н	NC	Hold
A data	B data	I	1	B data	Lotob and road register
A data	B data	h	1	A data	Latch and read register

#### Notes to function table

H = High-voltage level

High-voltage level one setup time before the low-to-high latch enable transition

L = Low-voltage level
I = Low-voltage level one setup time before the low-to-high latch enable transition
NC= No change ( If SELECT A/B is toggled and the A latched data is different from B latched data then the output will change accordingly.)

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Don't care

Low-to-high latch enable transition

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#### ABSOLUTE MAXIMUM RATINGS

(Operation beyond the limit set forth in this table may impair the useful life of the device.

Unless otherwise noted these limits are over the operating free air temperature range.)

SYMBOL	PARAMETER	RATING	UNIT
V <sub>CC</sub>	Supply voltage	-0.5 to +7.0	V
V <sub>IN</sub>	Input voltage	-0.5 to +7.0	V
I <sub>IN</sub>	Input current	-30 to +5	mA
V <sub>OUT</sub>	Voltage applied to output in high output state	−0.5 to V <sub>CC</sub>	V
l <sub>OUT</sub>	Current applied to output in low output state	40	mA
T <sub>amb</sub>	Operating free air temperature range	0 to +70	°C
T <sub>stg</sub>	Storage temperature range	-65 to +150	°C

#### **RECOMMENDED OPERATING CONDITIONS**

SYMBOL	PARAMETER		UNIT		
		MIN	NOM	MAX	1
V <sub>CC</sub>	Supply voltage	4.5	5.0	5.5	V
V <sub>IH</sub>	High-level input voltage	2.0			V
V <sub>IL</sub>	Low-level input voltage			0.8	V
I <sub>lk</sub>	Input clamp current			-18	mA
I <sub>OH</sub>	High-level output current			-1	mA
I <sub>OL</sub>	Low-level output current			20	mA
T <sub>amb</sub>	Operating free air temperature range	0		+70	°C

#### DC ELECTRICAL CHARACTERISTICS

(Over recommended operating free-air temperature range unless otherwise noted.)

SYMBOL	PARAMETER		TE			UNIT			
			COND	CONDITIONS <sup>1</sup>					
				$I_{OH} = -1 \text{mA}$	±10%V <sub>CC</sub>	2.5			V
V <sub>OH</sub>	High-level output voltage		$V_{CC} = MIN, V_{IL} = MAX,$		±5%V <sub>CC</sub>	2.7	3.4		V
		V <sub>IH</sub> = MIN	$I_{OH} = -3mA$	±10%V <sub>CC</sub>	2.4			V	
				±5%V <sub>CC</sub>	2.7	3.3		V	
V <sub>OL</sub>	Low-level output voltage		$V_{CC} = MIN, V_{IL} = MAX,$	I <sub>OL</sub> = MAX	±10%V <sub>CC</sub>		0.30	0.50	V
			V <sub>IH</sub> = MIN		±5%V <sub>CC</sub>		0.30	0.50	V
V <sub>IK</sub>	Input clamp voltage		$V_{CC} = MIN, I_I = I_{IK}$				-0.73	-1.2	V
I <sub>I</sub>	Input current at maximum input vo	ltage	$V_{CC} = MAX, V_I = 7.0V$					100	μА
I <sub>IH</sub>	High-level input current		$V_{CC} = MAX, V_I = 2.7V$					20	μА
I <sub>IL</sub>	Low-level input current	$V_{CC} = MAX, V_I = 0.5V$					-20	μΑ	
Ios	Short–circuit output current <sup>3</sup>		V <sub>CC</sub> = MAX			-60		-150	mA
Icc	Supply current (total)	I <sub>CCH</sub>	V <sub>CC</sub> = MAX				60	80	mA
		I <sub>CCL</sub>					75	100	mA

#### Notes to DC electrical characteristics

- 1. For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.
- 2. All typical values are at  $V_{CC}$  = 5V,  $T_{amb}$  = 25°C.
- 3. Not more than one output should be shorted at a time. For testing I<sub>OS</sub>, the use of high-speed test apparatus and/or sample-and-hold techniques are preferable in order to minimize internal heating and more accurately reflect operational values. Otherwise, prolonged shorting of a high output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests, I<sub>OS</sub> tests should be performed last.

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#### **AC ELECTRICAL CHARACTERISTICS**

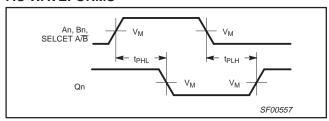
SYMBOL	PARAMETER	TEST CONDITION	V.	<sub>mb</sub> = +25 <sub>CC</sub> = +5.0 OpF, R <sub>L</sub> :	V	$T_{amb} = 0^{\circ}C$ $V_{CC} = +5.0$ $C_{L} = 50 \text{pF}$	UNIT	
			MIN	TYP	MAX	MIN	MAX	1
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay SELECT A/B to Qn (non–inverting)	Waveform 2	3.0 3.5	5.5 6.5	8.5 10.0	2.5 3.0	9.0 11.5	ns
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay SELECT A/B to Qn (inverting)	Waveform 1	4.0 2.5	7.0 4.5	10.5 7.5	3.5 2.0	12.0 8.0	ns
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay LE to Qn	Waveform 3	6.5 6.0	9.5 9.0	13.0 12.5	5.5 5.0	15.0 14.0	ns
t <sub>PLH</sub>	Propagation delay An or Bn to Qn	Waveform 1, 2	4.0 4.0	6.5 7.0	9.5 10.5	3.5 3.5	10.5 12.5	ns

#### **AC SETUP REQUIREMENTS**

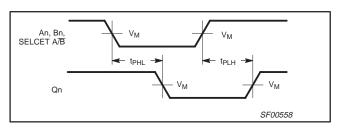
SYMBOL	PARAMETER	TEST		<sub>mb</sub> = +25° <sub>CC</sub> = +5.0		$T_{amb} = 0^{\circ} C$ $V_{CC} = +5.$	UNIT	
	. /	CONDITION	$C_D = 50 \text{pF}, R_L = 500 \Omega$			C <sub>D</sub> = 50pF,		
			MIN	TYP	MAX	MIN	MAX	1 1
t <sub>su</sub> (H) t <sub>su</sub> (L)	Setup time, high or low An, Bn to $\overline{\text{LE}}$	Waveform 4	0.0 1.0			0.0 3.5		ns
t <sub>h</sub> (H) t <sub>h</sub> (L)	Hold time, high or low An, Bn to LE	Waveform 4	1.5 3.0			2.0 3.5		ns
t <sub>w</sub> (L)	LE Pulse width, low	Waveform 4	6.5			7.5		ns

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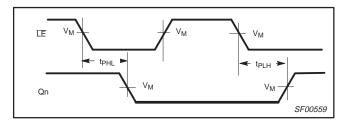
#### **AC WAVEFORMS**



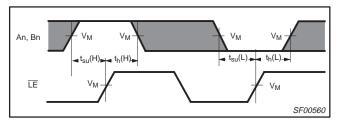
Waveform 1. Propagation delay for SELECT A/ $\overline{B}$  to output (A register stored data = low) or An. Bn to output



Waveform 2. Propagation delay for SELECT A/ $\overline{B}$  to output (A register stored data = low) or An. Bn to output



Waveform 3. Propagation delay for latch enable to output



Waveform 4. Setup time and hold times and  $\overline{\text{LE}}$  pulse width

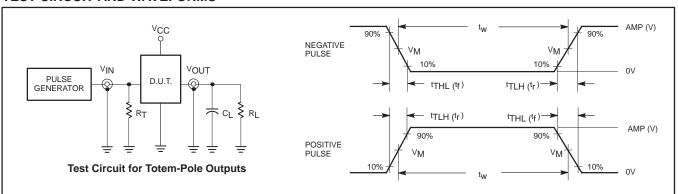
#### Note to AC waveforms

For all waveforms,  $V_M = 1.5V$ .

The shaded areas indicate when the input is permitted to change for predictable output performance.

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#### **TEST CIRCUIT AND WAVEFORMS**



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#### **DEFINITIONS:**

R<sub>L</sub> = Load resistor; see AC ELECTRICAL CHARACTERISTICS for value.

C<sub>L</sub> = Load capacitance includes jig and probe capacitance; see AC ELECTRICAL CHARACTERISTICS for value.

R<sub>T</sub> = Termination resistance should be equal to Z<sub>OUT</sub> of

pulse generators.

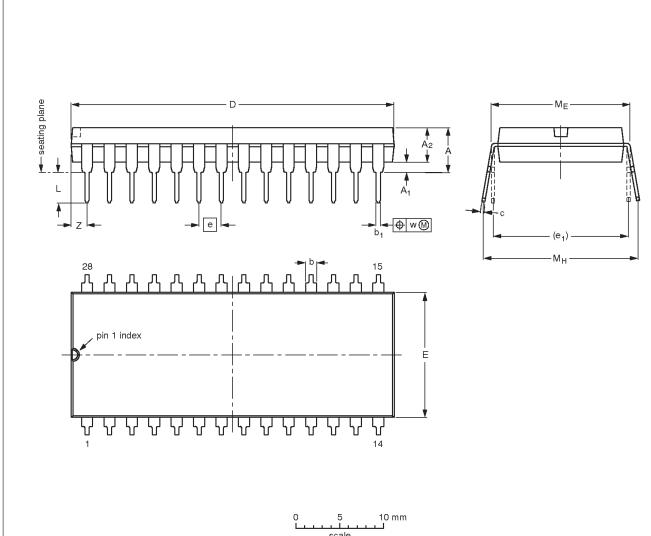
family	INP	INPUT PULSE REQUIREMENTS										
	amplitude	$V_{\text{M}}$	rep. rate	t <sub>w</sub>	t <sub>TLH</sub>	t <sub>THL</sub>						
74F	3.0V	1.5V	1MHz	500ns	2.5ns	2.5ns						

SF00006

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#### DIP28: plastic dual in-line package; 28 leads (600 mil); long body

SOT117-2



### scale

#### DIMENSIONS (millimetre dimensions are derived from the original inch dimensions)

UNIT	A max.	A <sub>1</sub> min.	A <sub>2</sub> max.	b	b <sub>1</sub>	С	D <sup>(1)</sup>	E <sup>(1)</sup>	e	e <sub>1</sub>	L	ME	Мн	w	Z <sup>(1)</sup> max.
mm	5.08	0.51	3.94	1.63 1.14	0.56 0.43	0.38 0.25	37.08 35.94	14.22 13.84	2.54	15.24	3.51 3.05	15.75 15.24	17.65 15.24	0.25	2.10
inches	0.200	0.020	0.155	0.064 0.045	0.022 0.017	0.015 0.010	1.460 1.415	0.560 0.545	0.100	0.600	0.138 0.120	0.62 0.60	0.695 0.600	0.01	0.083

1. Plastic or metal protrusions of 0.01 inches maximum per side are not included.

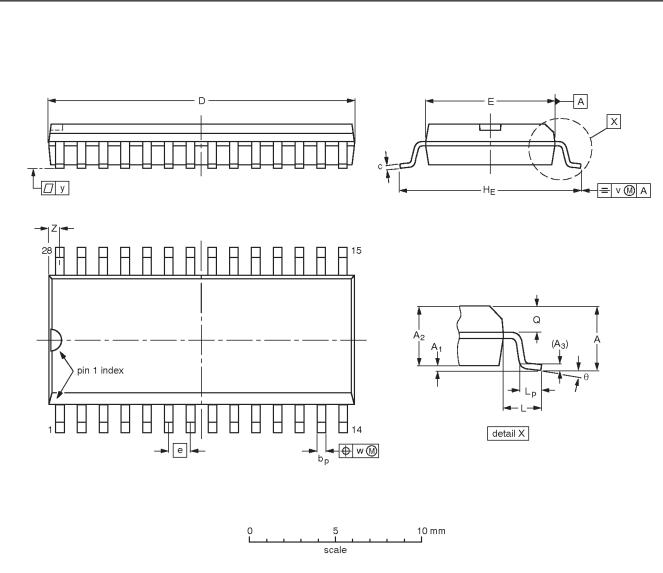
OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT117-2		MS-011AB			€	95-03-11

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#### SO28: plastic small outline package; 28 leads; body width 7.5mm

SOT136-1



#### DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	bp	С	D <sup>(1)</sup>	E <sup>(1)</sup>	е	HE	L	Lp	Q	v	w	у	z <sup>(1)</sup>	θ
mm	2.65	0.30 0.10	2.45 2.25	0.25	0.49 0.36	0.32 0.23	18.1 17.7	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8°
inches	0.10	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.71 0.69	0.30 0.29	0.050	0.419 0.394	0.055	0.043 0.016		0.01	0.01	0.004	0.035 0.016	0°

#### Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE		REFER	RENCES	EUROPEAN	ISSUE DATE			
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE			
SOT136-1	075E06	MS-013AE			<del>-95-01-24</del> 97-05-22			

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#### **NOTES**

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#### Data sheet status

Data sheet status	Product status	Definition [1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
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